

**SYSTEM FOR RINSING AND DRYING SEMICONDUCTOR SUBSTRATES
AND METHOD THEREFOR**

ABSTRACT OF THE DISCLOSURE

A system and method for cleaning and drying semiconductor wafers improves device yield by providing more advanced control of the ratio of drying fluid to cleaning fluid, for example the ratio of N₂ vapor to IPA vapor. In addition, a quick drain process is employed to improve process throughput, and to further improve particle and watermark removal during the cleaning and drying steps.

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